REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add case outline "X". Change made to 1.5. Changes also made to V_{OUT}, V_{RLINE}, V_{RLOAD}, ΔI_{SCD} (LOAD), I_{OL}, I_{OS}, NO, $\Delta V_{OUT}/\Delta I_L$, and $\Delta V_{IN}/\Delta V_{OUT}$ in table I. -rrp	99-04-28	R. MONNIN

REV																			
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SHEET																			

REV STATUS	REV	A	A	A	A	A	A	A	A	A	A	A	A	A
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	

PMIC N/A

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DRAWING APPROVAL DATE
99-04-05

REVISION LEVEL
A

DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216

STANDARD MICROCIRCUIT DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

MICROCIRCUIT, LINEAR, RADIATION HARDENED, POSITIVE, VOLTAGE REGULATOR, MONOLITHIC SILICON

SIZE	CAGE CODE	
A	67268	5962-99551

SHEET 1 OF 12

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:

5962	R	99551	01	Q	X	X
Federal stock class designator	RHA designator (see 1.2.1)		Device type (see 1.2.2)	Device class designator (see 1.2.3)	Case outline (see 1.2.4)	Lead finish (see 1.2.5)

Drawing number

1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	LM140H-5.0	Voltage regulator, +5 V at 0.5 A

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
X	See figure 1	3	TO-39 Can
Y	MBFM1-P2	2	Flange mount

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

DC input voltage (VIN)	35 V
Power dissipation:	Internally limited 2/
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	300°C
Maximum junction temperature (T_J)	150°C
Thermal resistance, junction-to-case (θ_{JC})	15°C/W
Thermal resistance, junction-to-ambient (θ_{JA})	232°C/W Still air 77°C/W 500 LFPM air flow

1.4 Recommended operating conditions.

Ambient operating temperature range (T_A)	-55°C to +125°C

1.5 Radiation features.

Maximum total dose available (dose rate = 50 – 300 rads (Si)/s):
Device classes Q and V ..... 100 Krads

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ The maximum allowable power dissipation at any ambient temperature is a function of maximum T_J, θ_{JA}, and T_A. $P_D = (T_{JMAX} - T_A)/\theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C, the device will go into thermal shutdown. When using a heatsink, θ_{JA} is the sum of θ_{JC} and the case-to-ambient thermal resistance (θ_{CA}) of the heatsink.

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be as specified on figure 3.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

3.9 Verification and review for device class M. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 52 (see MIL-PRF-38535, appendix A).

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions 1/ 2/ -55°C ≤ T_A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Output voltage	V_{OUT}	V_{IN} = 8 V, I_L = -5 mA	1, 2, 3	01	4.75	5.25	V
		V_{IN} = 8 V, I_L = -500 mA	1, 2, 3	01	4.75	5.25	
		V_{IN} = 20 V, I_L = -5 mA	1, 2, 3	01	4.75	5.25	
		V_{IN} = 20 V, I_L = -500 mA	1, 2, 3	01	4.75	5.25	
		V_{IN} = 35 V, I_L = -5 mA	1, 2, 3	01	4.75	5.25	
		V_{IN} = 35 V, I_L = -50 mA	1, 2, 3	01	4.75	5.25	
Line regulation	V_{RLINE}	8 V ≤ V_{IN} ≤ 35 V, I_L = -50 mA	1, 2, 3	01	-150	150	mV
		8 V ≤ V_{IN} ≤ 25 V, I_L = -350 mA	1, 2, 3	01	-50	50	
Load regulation	V_{RLOAD}	V_{IN} = 10 V -500 mA ≤ I_L ≤ -5 mA	1, 2, 3	01	-100	100	mV
		V_{IN} = 35 V -50 mA ≤ I_L ≤ -5 mA	1, 2, 3	01	-150	150	
Standby current drain	I_{SCD}	V_{IN} = 10 V I_L = -5 mA	1, 2, 3	01	-7	-0.5	mA
		V_{IN} = 35 V I_L = -5 mA	1, 2, 3	01	-8	-0.5	
Standby current drain versus line voltage	ΔI_{SCD} (LINE)	8 V ≤ V_{IN} ≤ 35 V, I_L = -5 mA	1, 2, 3	01	-1	1	mA
Standby current drain versus load current	ΔI_{SCD} (LOAD)	V_{IN} = 10 V, -500 mA ≤ I_L ≤ -5 mA	1, 2, 3	01	-0.5	0.5	mA
Overload current	I_{OL}	V_{IN} = 8 V, Forced ΔV_{OUT} = -0.48 V	1, 2, 3	01	-2	-0.5	A
Output short circuit current	I_{OS}	V_{IN} = 10 V	1, 2, 3	01	-2	-0.01	A
		V_{IN} = 25 V	1, 2, 3	01	-1.5	-0.01	
		V_{IN} = 35 V	1, 2, 3	01	-1	-0.01	
Output voltage	V_{OUT}	V_{IN} = 10 V, I_L = -5 mA T_A = +125°C 3/	2	01	4.7	5.3	V
Output voltage	V_{OUT}	V_{IN} = 10 V, I_L = -5 mA 4/	1, 2, 3	01	4.75	5.25	V

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions 1/ 2/ -55°C ≤ T_A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Average temperature coefficient output voltage	$\Delta V_{OUT}/\Delta T$	V_{IN} = 10 V, I_L = -5 mA 5/	2, 3	01	-2	2	mV/°C
Output noise voltage	NO	V_{IN} = 10 V, I_L = -50 mA T_A = +25°C	9	01		125	µVrms
Transient line response	$\Delta V_{OUT}/\Delta V_{IN}$	V_{IN} = 10 V, V_{PULSE} = 3 V, I_L = -5 mA , T_A = +25°C	9	01		30	mV/V
Transient load response	$\Delta V_{OUT}/\Delta I_L$	V_{IN} = 10 V, ΔI_L = -200 mA, I_L = -50 mA , T_A = +25°C	9	01		2.5	mV/mA
Ripple rejection	$\Delta V_{IN}/\Delta V_{OUT}$	V_{IN} = 10 V, ei = 1 Vrms at f = 2400 Hz, I_L = -125 mA, T_A = +25°C	9	01	60		dB

1/ Devices supplied to this drawing have been characterized through all levels M, D, P, L, R of irradiation. However, this device is only tested at the "R" level. Pre and Post irradiation values are identical unless otherwise specified in table I.
2/ These parts may be dose rate sensitive in a space environment and demonstrate enhanced low dose rate effect. Radiation end point limits for the conditions as specified in MIL-STD-883, Method 1019 condition A.
3/ Tested at T_A = +125°C, correlated to T_A = +150°C.
4/ Tested at extremes as a set up for $\Delta V_{OUT}/\Delta T$ tests.
5/ Calculated parameter.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.

(2) T_A = +125E C, minimum.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

Case X

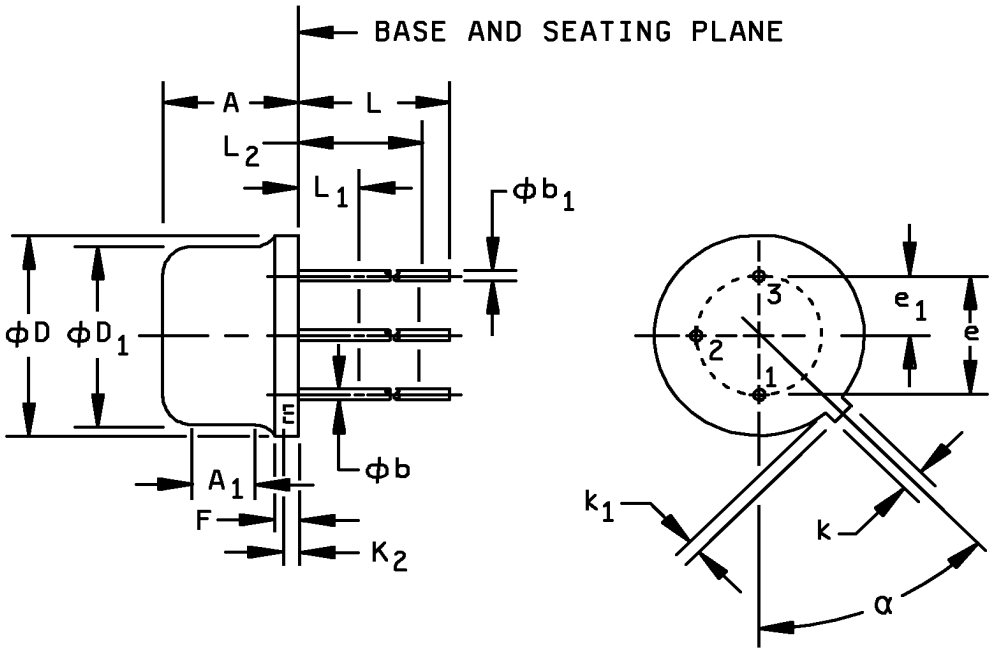


FIGURE 1. Case outline.

Case X

Symbol	Inches		Millimeters		Notes
	Min	Max	Min	Max	
A	.165	.195	4.19	4.95	
A_1	.100	----	2.54	----	7
ϕb	.016	.019	0.41	0.48	3
ϕb_1	.016	.021	0.41	0.53	3
ϕD	.335	.370	8.51	9.40	
ϕD_1	.305	.335	7.75	8.51	
e	.200 BSC		5.08 BSC		5
e_1	.100 BSC		2.54 BSC		5
F	----	.050	----	1.27	
k	.028	.034	0.71	0.86	
k_1	.029	.045	0.74	1.14	4
k_2	.009	.041	0.23	1.04	
L	.500	----	12.70	----	
L_1	----	.050	----	1.27	
L_2	.250	----	6.35	----	
α	45° T.P.		45° T.P.		5

NOTES:

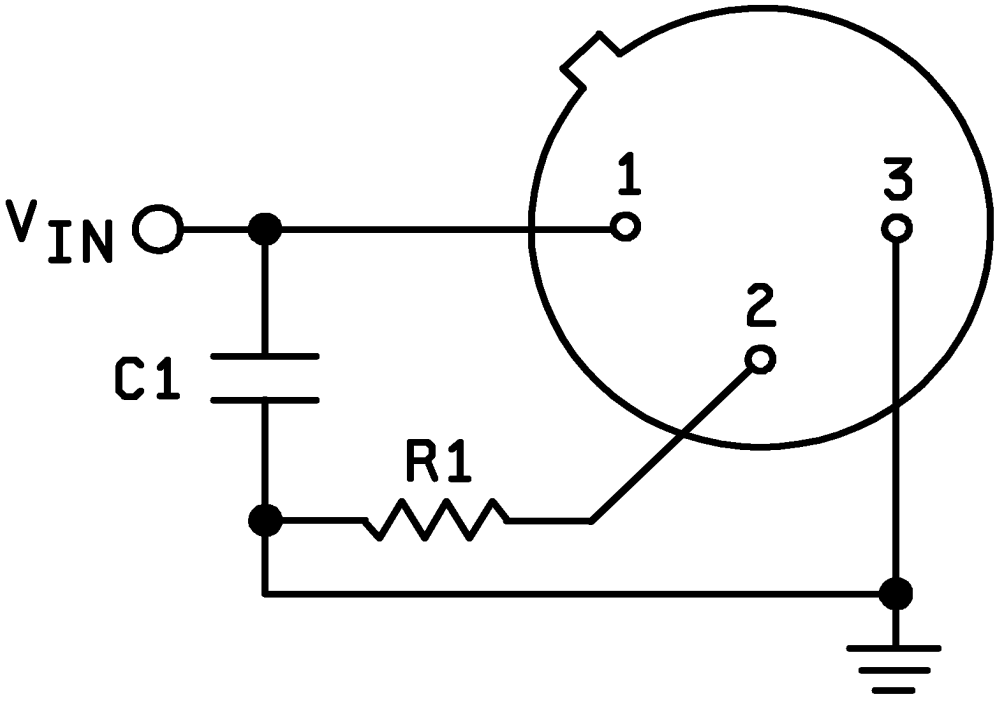
1. The US government preferred system of measurement is the metric SI system. However, this item was originally designed using inch-pound units of measurement. In the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
2. ϕb applies between L_1 and beyond .500 inch (12.70 mm) from the seating plane (two leads). Diameter is uncontrolled in L_1 and beyond .500 inch (12.70 mm) from the seating plane.
3. Two leads.
4. Two holes.
5. Two holes located at true position within diameter .010 inch (0.25 mm).
6. Leads having a maximum diameter of .043 inch (1.09 mm) measured in gauging plane .054 inch (1.37 mm) ± .001 (0.03 mm) .000 inch (0.00 mm) below the seating plane shall be located at true position within diameter .014 inch (0.36 mm).
7. The mounting surface of the header shall be flat to convex within .003 inch (0.08 mm) inside a .930 inch (23.62 mm) diameter circle on the center of the header and flat to convex within .006 inch (0.15 mm) overall.

FIGURE 1. Case outline – Continued.

Device type	01	
Case outline	X	Y
Terminal number	Terminal symbol	
1	INPUT	INPUT
2	OUTPUT	OUTPUT
3	GND	----

NOTE: For case outline Y, case is ground.

FIGURE 2. Terminal connections.



NOTES:
1. V_{IN} = 10.0 V min to 11.5 V max
2. R1 = 1 kΩ 1/4 W
3. C1 = 0.1 µF

FIGURE 3. Radiation exposure circuit.

4.2.2 Additional criteria for device classes Q and V.

a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table IIA herein.

c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

a. Tests shall be as specified in table IIA herein.

b. Subgroups 4, 5, 6, 7, 8, 10, and 11in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

b. T_A = +125E C, minimum.

c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical Parameters (see 4.2)	1	1	1
Final electrical Parameters (see 4.2)	1, 2, 3, 9 1/	1, 2, 3, 9 1/	1, 2, 3, 9, 1/
Group A test Requirements (see 4.4)	1, 2, 3, 9	1, 2, 3, 9	1, 2, 3, 9
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2,3	1, 2, 3 2/
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	1	1	1

1/ PDA applies to subgroup 1.
2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous endpoint electrical parameters.

Table IIB. Group C end-point electrical parameters. T_A = 25°C

Parameter	Device type	Delta limit	
		Min	Max
V_{OUT}	V_{IN} = 8 V, I_L = -5 mA	-0.025 V	0.025 V
	V_{IN} = 8 V, I_L = -500 mA	-0.025 V	0.025 V
	V_{IN} = 20 V, I_L = -5 mA	-0.025 V	0.025 V
	V_{IN} = 20 V, I_L = -500 mA	-0.025 V	0.025 V
	V_{IN} = 35 V, I_L = -5 mA	-0.025 V	0.025 V
	V_{IN} = 35 V, I_L = -50 mA	-0.025 V	0.025 V
I_{SCD}	V_{IN} = 10 V, I_L = -5 mA	-20%	20%

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes M, Q, and V shall be as specified in MIL-I-38535. End-point electrical parameters shall be as specified in table IIA herein.

4.4.4.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019 condition A and as specified herein.

4.4.4.1.1 Accelerated aging test. Accelerated aging tests shall be performed on all devices requiring a RHA level greater than 5k rads(Si). The post-anneal end-point electrical parameter limits shall be as specified in table I herein and shall be the pre-irradiation end-point electrical parameter limit at 25°C ±5°C. Testing shall be performed at initial qualification and after any design or process changes which may affect the RHA response of the device.

4.4.4.2 Dose rate burnout. When required by the customer test shall be performed on devices, SEC, or approved test structures at technology qualifications and after any design or process changes which may effect the RHA capability of the process. Dose rate burnout shall be performed in accordance with test method 1023 of MIL-STD-883 and as specified herein.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 99-04-28

Approved sources of supply for SMD 5962-99551 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962R9955101QYA	3/	LM140K-5.0RQML
5962R9955101VYA	3/	LM140K-5.0RQMLV
5962R9955101QXA	27014	LM140H-5.0RQML
5962R9955101VXA	27014	LM140H-5.0RQMLV

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
3/ Not available from an approved source of supply.

Vendor CAGE number	Vendor name and address
27014	National Semiconductor 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.